# Special Issue

## Biodegradable Packaging Used in the Food Industry

### Message from the Guest Editors

An ecological concern of the modern world is reducing the environmental impact of packaging by finding alternatives for plastic. Food packaging should not simply play a passive role in protecting and marketing a food product. Thus, the new concepts of active and intelligent packaging will play an increasingly important role, offering innovative solutions for extending shelf life or maintaining, improving, or monitoring food quality and safety. New food packaging technologies are developing in response to consumer demands or industrial production trends towards easy-to-preserve, fresh, tasty, and affordable food products with extended shelf lives and safety. One solution may be to use starch as a bioplastic. Considerable improvements in the properties of starch films have been reported with the production of composite materials or blends, and obtaining active and/or smart films using various additives.

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### Guest Editors

Prof. Dr. Ovidiu Tita

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### Deadline for manuscript submissions

closed (20 November 2024)

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

## Editor-in-Chief

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